

P-Channel 20-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q_g			
	$0.094 \text{ at V}_{GS} = -4.5 \text{ V}$	- 4.5				
- 20	0.131 at V _{GS} = -2.5 V	- 4.5	4.9 nC			
	0.185 at V _{GS} = - 1.8 V	- 4.5				

SCHOTTKY PRODUCT SUMMARY					
V _{KA} (V)	V _f (V) Diode Forward Voltage	I _F (A) ^a			
20	0.46 at 0.5 A	1			

PowerPAK SC-70-6 Dual

FEATURES

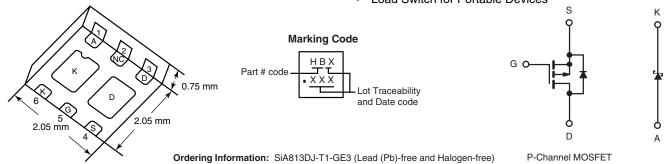
- Halogen-free According to IEC 61249-2-21 Definition
- LITTLE FOOT[®] Plus Schottky Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-70 Package
 - Small Footprint Area
 - Low On-Resistance
 - Thin 0.75 mm Profile
- Compliant to RoHS Directive 2002/95/EC

Pb-free

ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- · Cellular Charger Switch
- Buck Converter for Portable Devices
- Load Switch for Portable Devices



Parameter		Symbol	Limit	Unit
Drain-Source Voltage (MOSFET)		V _{DS}	- 20	v
Reverse Voltage (Schottky)		V _{KA}	20	
Gate-Source Voltage (MOSFET)		V_{GS}	± 8	
	T _C = 25 °C		- 4.5 ^a	
Continuous Drain Current (T _{.I} = 150 °C) (MOSFET)	T _C = 70 °C		- 4.5 ^a	
Continuous Diain Current (1, = 150 C) (MOSFET)	T _A = 25 °C	I _D	- 3.6 ^{b, c}	
	T _A = 70 °C		- 2.9 ^{b, c}	
Pulsed Drain Current (MOSFET)		I _{DM}	- 8	A
Continuous Source-Drain Diode Current	T _C = 25 °C	I.	- 4.5 ^a	
(MOSFET Diode Conduction)	T _A = 25 °C	I _S	- 1.6 ^{b, c}	
Average Forward Current (Schottky)		I _F	1 ^b	
Pulsed Forward Current (Schottky)	I _{FM}	2		
	T _C = 25 °C		6.5	
Maximum Power Dissipation (MOSFET)	T _C = 70 °C		5	
Maximum Fower Dissipation (MOSFET)	T _A = 25 °C		1.9 ^{b, c}	
	T _A = 70 °C	P _D	1.2 ^{b, c}	w
	T _C = 25 °C	' b	7.3	VV
Maximum Power Dissipation (Schottky)	T _C = 70 °C		4.7	
Maximum Fower Dissipation (Schottky)	T _A = 25 °C		2.3 ^{b, c}	
	T _A = 70 °C		1.5 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature) d, e		260		

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THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient (MOSFET) ^{b, f}	t ≤ 5 s	R _{thJA}	52	65				
Maximum Junction-to-Case (Drain) (MOSFET)	Steady State	R_{thJC}	12.5	16	°C/W			
Maximum Junction-to-Ambient (Schottky) ^{b, g}	t ≤ 5 s	R_{thJA}	40	55	C/VV			
Maximum Junction-to-Case (Drain) (Schottky)	Steady State	R_{thJC}	13	17				

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. See solder profile (<u>www.vishay.com/ppg?73257</u>). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions for MOSFET is 110 $^{\circ}$ C/W.
- g. Maximum under steady state conditions for Schottky is 85 $^{\circ}\text{C}.$

Parameter Symbol		Test Conditions		Тур.	Max.	Unit	
Static						•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Ι _D = - 250 μΑ		- 16.2		mV/°0	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = -200 μΑ		2.1		illv/ C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	l	V _{DS} = - 20 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	IDSS	V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 8			Α	
Drain-Source On-State Resistance ^a		V _{GS} = - 4.5 V, I _D = - 2.8 A		0.078	0.094		
	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 2.3 A		0.109	0.131	Ω	
		V _{GS} = - 1.8 V, I _D = - 0.54 A		0.153	0.185		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 2.8 A		7		S	
Dynamic ^b							
Input Capacitance	C _{iss}			355			
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		75		pF	
Reverse Transfer Capacitance	C _{rss}			50			
Total Cata Charge	Qg	$V_{DS} = -10 \text{ V}, V_{GS} = -8 \text{ V}, I_D = -4.5 \text{ A}$		8.5	13		
Total Gate Charge				4.9	7.4		
Gate-Source Charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.5 \text{ A}$		0.75		nC	
Gate-Drain Charge	Q _{gd}			1.2			
Gate Resistance	R _g	f = 1 MHz		8		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 2.2 \Omega$		35	55	1	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 4.5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	60	1	
Fall Time	t _f			50	75		
Turn-On Delay Time	t _{d(on)}			5	10	ns	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 2.2 \Omega$		10	15	1	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -4.5 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$		20	30	1	
Fall Time	t _f	1		10	15	1	



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SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions Min.		Тур.	Max.	Unit	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.5	Α	
Pulse Diode Forward Current	I _{SM}				- 8	A	
Body Diode Voltage	V_{SD}	$I_S = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.85	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 4.5 A, dl/dt = 100 A/μs, T _J = 25 °C		13	26	nC	
Reverse Recovery Fall Time	t _a	- 1μ = -4.5 A, αί/αι = 100 A/μ3, 1 J = 23 · O		10		ns	
Reverse Recovery Rise Time	t _b			15		1	

Notes:

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

SCHOTTKY SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
		I _F = 0.5 A		0.381	0.46		
Forward Voltage Drop	V _F	I _F = 1 A		0.468	0.560	V	
		I _F = 1 A, T _J = 125 °C		0.44	0.53		
		V _r = 5 V		0.0081	0.041	mA	
	I _{rm}	V _r = 5 V, T _J = 85 °C		0.4	4		
		V _r = 5 V, T _J = 125 °C		2.8	28		
		V _r = 10 V		0.0085	0.043		
Maximum Reverse Leakage Current		V _r = 10 V, T _J = 85 °C		0.5	5		
		$V_r = 10 \text{ V}, \ T_J = 125 ^{\circ}\text{C}$		3	30		
		V _r = 20 V		0.0093	0.4 4 2.8 28 0.0085 0.043 0.5 5 3 30		
		V _r = 20 V, T _J = 85 °C		0.5	5		
		V _r = 20 V, T _J = 125 °C		3.2	32		
Junction Capacitance	C _T	V _r = 10 V		30		pF	

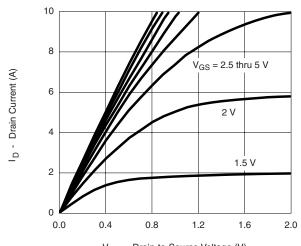
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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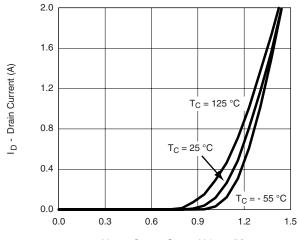
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MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

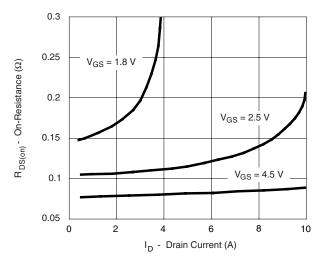


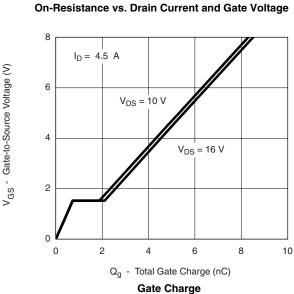
 $V_{DS}\,$ - Drain-to-Source Voltage (V)



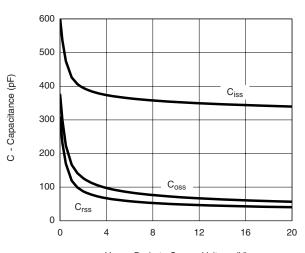
V_{GS} - Gate-to-Source Voltage (V)

Output Characteristics



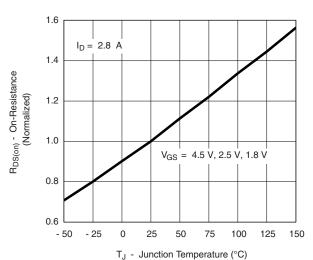


Transfer Characteristics



V_{DS} - Drain-to-Source Voltage (V)

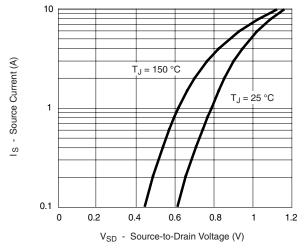
Capacitance



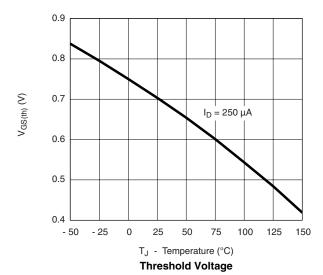
On-Resistance vs. Junction Temperature

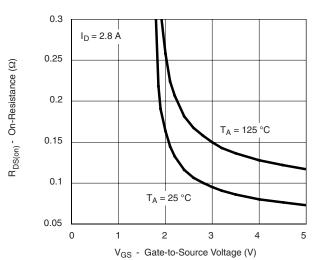


MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

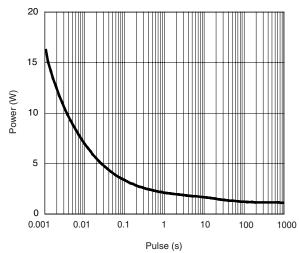


Soure-Drain Diode Forward Voltage

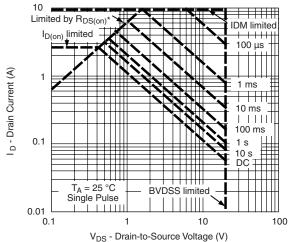




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area, Junction-to-Case

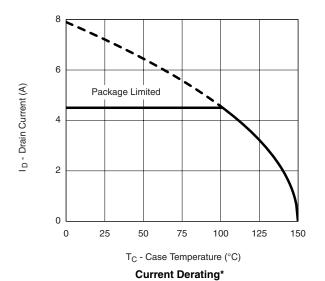
Power Dissipation (W)

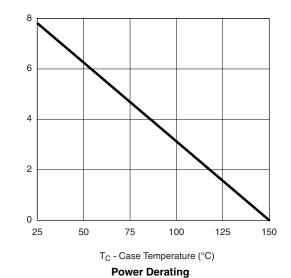
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MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

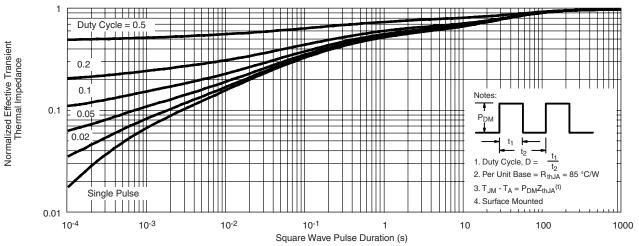




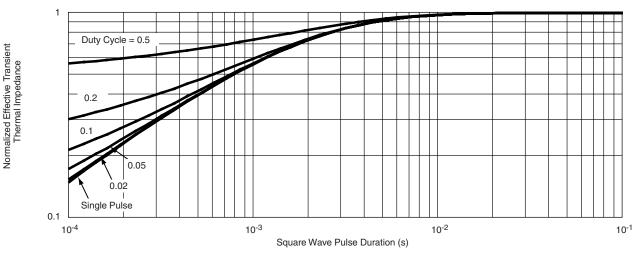
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

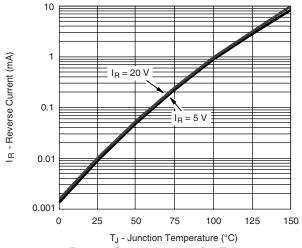
Is - Source Current (A)

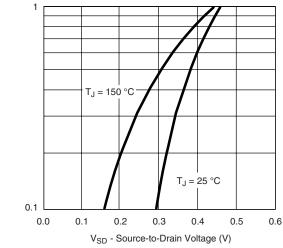
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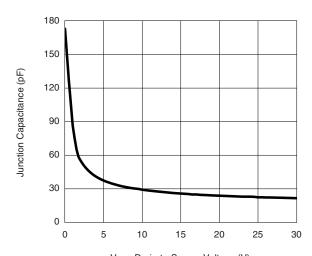
SCHOTTKY TYPICAL CHARACTERISTICS $T_A = 25~^{\circ}C$, unless otherwise noted





Reverse Current vs. Junction Temperature

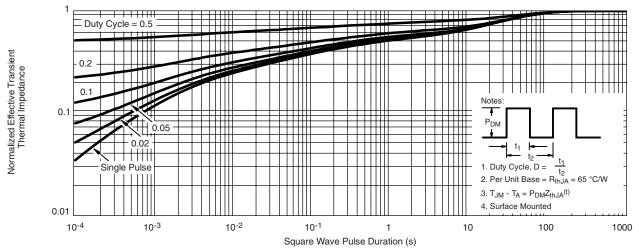
Forward Voltage Drop



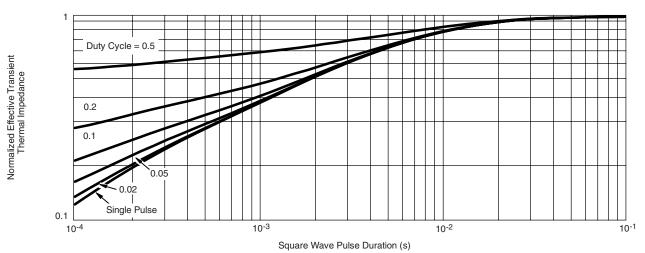
V_{DS} - Drain-to-Source Voltage (V)



SCHOTTKY TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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